



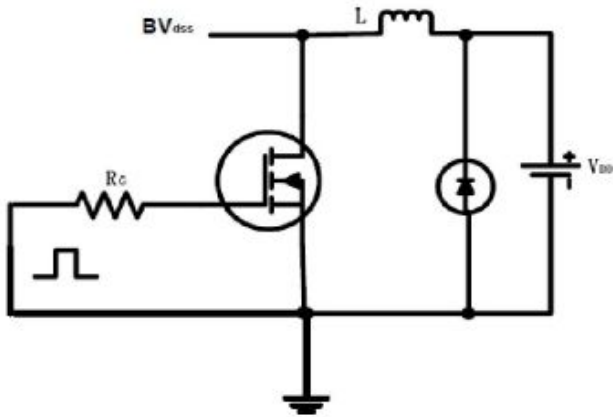
电气特性 (T_c = 25°C)

符号	参数	Conditions	最小值	典型值	最大值	单位
V(BR)DSS	漏极到源极关断电压	VGS = 0V, ID = 250μA	20	—	—	V
RDS(on)	静态漏极源极导通电阻	VGS=4.5V, ID = 1A	—	13	18	mΩ
		VGS=2.5V, ID=1A		15	22	
VGS(th)	栅极阈值电压	VDS = VGS, ID = 250μA	0.45	0.6	1.0	V
IDSS	漏极源极电流	VDS = 16V, VGS = 0V	—	—	1	μA
IGSS	栅极源极电流	VGS = 12V	—	—	100	nA
		VGS = -12V	—	—	-100	
VSD	二极管正向电压	IS=8A, VGS=0V	—	0.73	1.3	V
Qg	栅极总电荷	ID = 5A, ID = 5A, VGS = 10V	—	24.1	—	nC
Qgs	栅极到源极电荷		—	1.4	—	
Qgd	栅极到漏极电荷		—	4.2	—	
td(on)	开启延迟时间	VGS=4V, VDS = 10V, RL=2.86Ω, ID = 3.5A	—	5.3	—	nS
tr	上升时间		—	18.2	—	
td(off)	关断延迟时间		—	25	—	
tf	下降时间		—	3	—	
Ciss	输入电容	VGS = 0V, VDS = 10V, f = 1MHz	—	681	—	pF
Coss	输出电容		—	124	—	
Crss	反向传输电容		—	117	—	

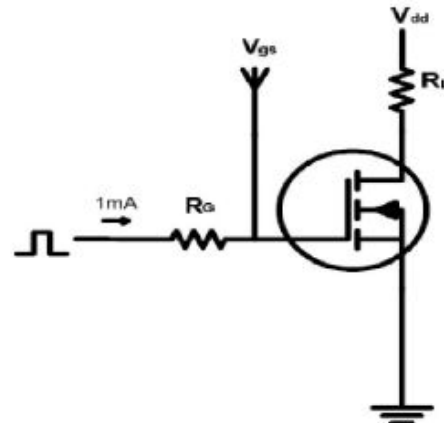


测试电路和波形

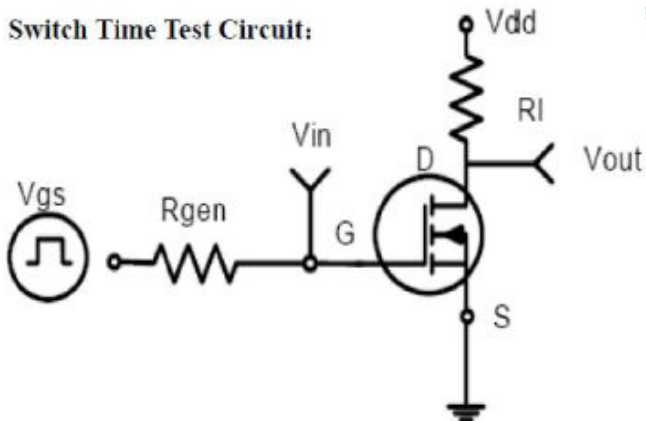
EAS test circuits:



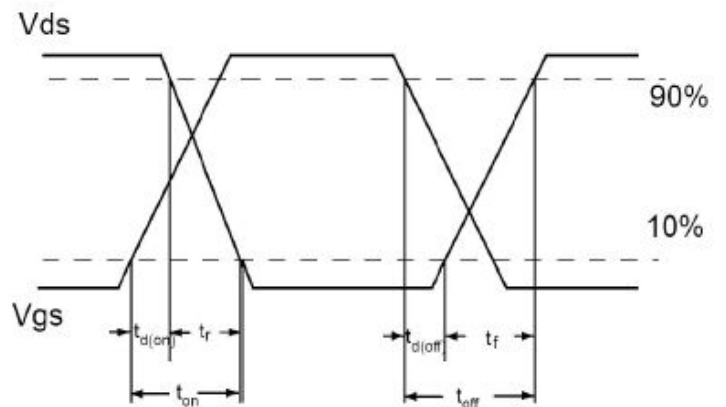
Gate charge test circuit:



Switch Time Test Circuit:



Waveforms:





典型的电气和热特性

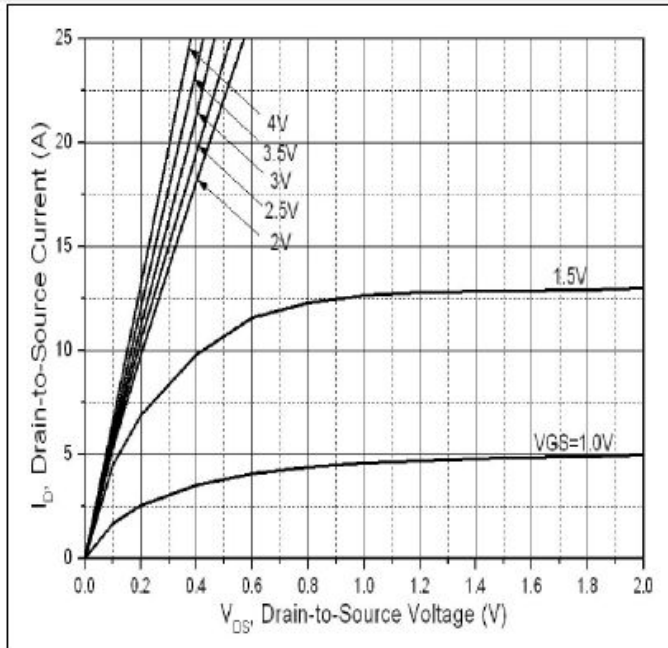


Figure 1: Typical Output Characteristics

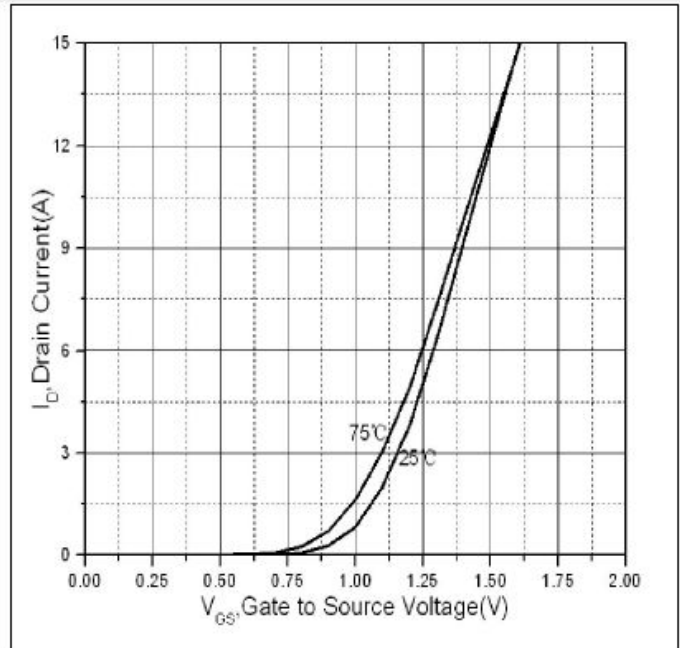


Figure 2: Typical Transfer Characteristics

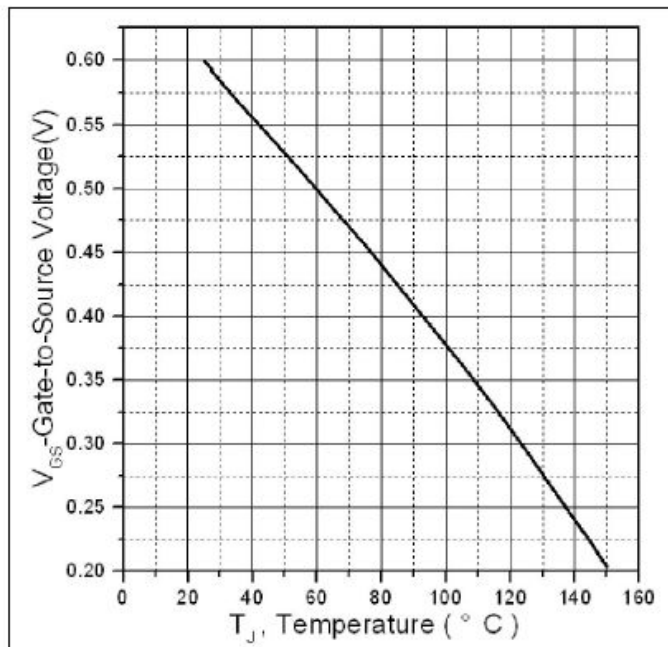


Figure 3: Gate to source cut-off voltage

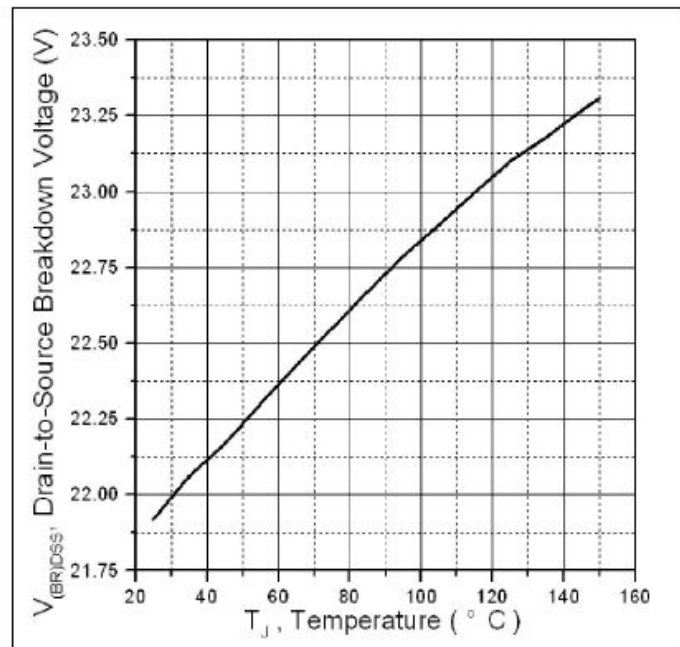


Figure 4: Drain-to-Source Breakdown Voltage vs. Temperature

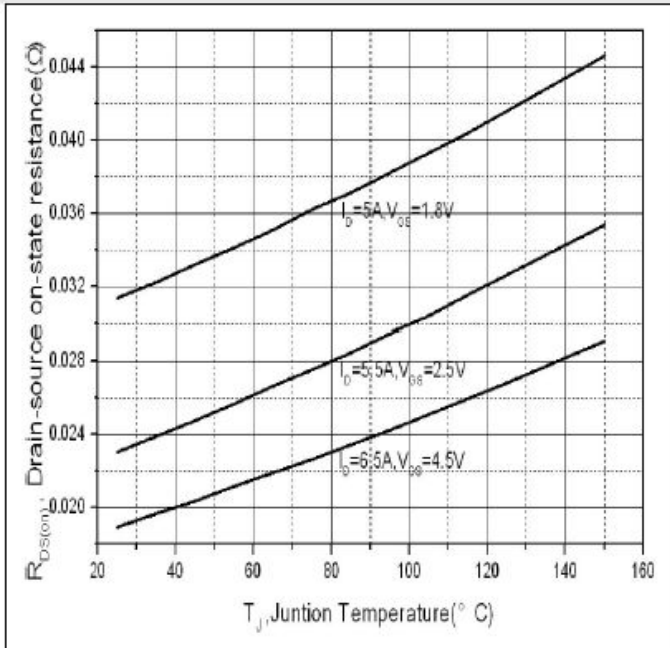


Figure 5. Normalized On-Resistance Vs. Case Temperature

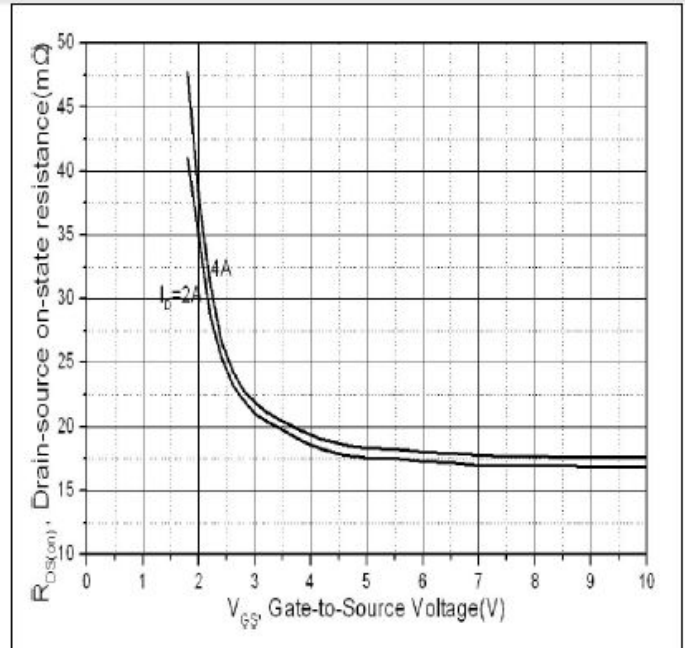


Figure 6. Normalized On-Resistance Vs. Gate to Source voltage

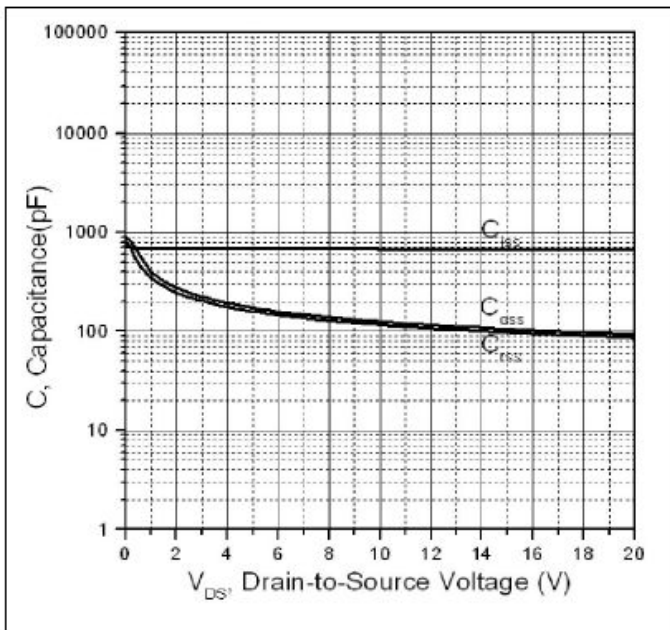


Figure 7. Typical Capacitance Vs. Drain-to-Source Voltage

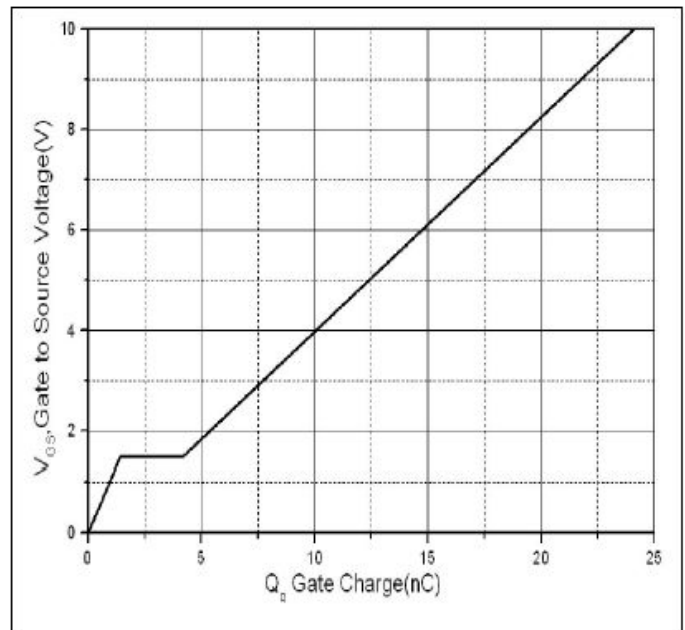


Figure 8. Gate-Charge Characteristics

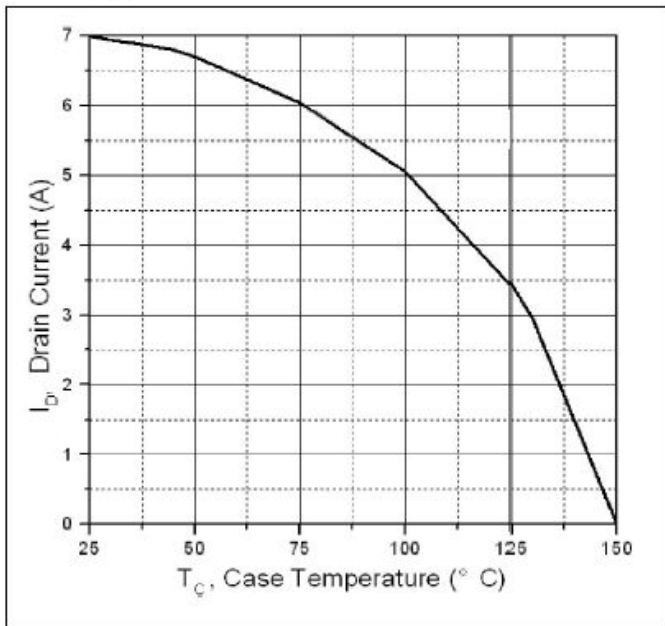


Figure9. Maximum Drain Current Vs. Case Temperature

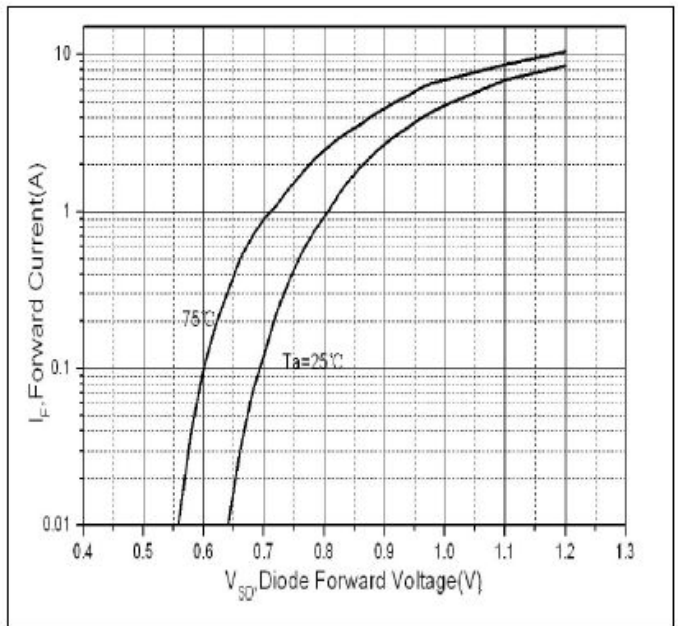


Figure10. Forward Current Vs. Diode Forward Voltage

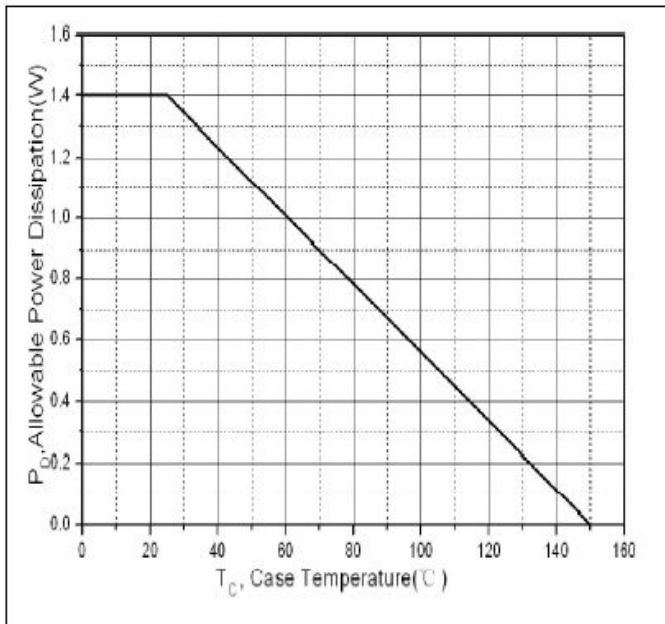
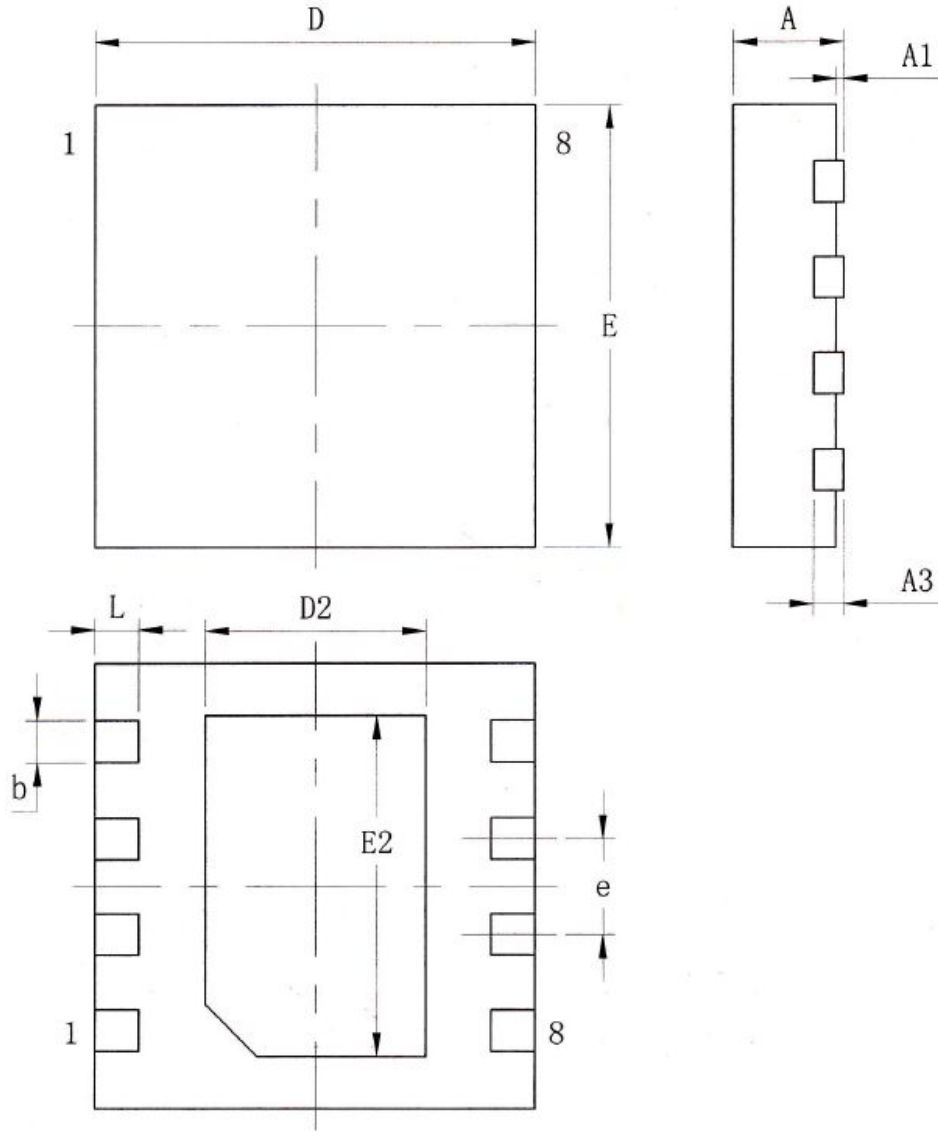


Figure11. Power Dissipation Vs. Case Temperature



封装信息



标注	最小值	标准值	最大值	标注	最小值	标准值	最大值
A	0.70	0.75	0.80	E	2.90	3.00	3.10
A1	—	—	0.05	D2	1.40	1.50	1.60
A3	0.203 REF			E2	2.20	2.30	2.40
b	0.23	0.28	0.33	e	0.65 TYP		
D	2.90	3.00	3.10	L	0.25	0.30	0.35